

To: Technology Center 2800
Facsimile Number: ~~792-972-9886~~

NOV 11 2005

Total Pages Sent 13

From: Charles A. Brill
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-4379

571-273-8306

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by
facsimile to the U.S. Patent and Trademark Office on the date
shown below:


Charles A. Brill

November 11, 2005
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT (11 Pages)
<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> EOT (2 Month)
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL BRIEF (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> REPLY BRIEF (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> PETITION
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): Mezenner	
RECEIPT DATE & SERIAL NO.: Application No.: 10/749,277	
TITLE OF INVENTION: VIA ADHESION IN MULTILAYER MEMS STRUCTURE	
Filing Date: 31 December 2003	
TI FILE NO.: TI-33824	DEPOSIT ACCT. NO.: 20-0668
FAXED: 11/11/2005 DUE: 9/12/2005 ATTY/SECY: CAB:ss	

RECEIVED
OIP/EIAP

NOV 15 2005

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265